DEVICE MIGRATION

Generic Copy

ISSUE DATE: 01-Jul-2015
NOTIFICATION: 16724
TITLE: Mitsui Assembly Site Closure and Package Migration Motor Drivers
LAST BUY DATE: 30-Sep-2015
LAST SHIP DATE: 31-Mar-2016

DEVICE(S)

MPN	REPLACEMENT MPN	REPLACEMENT TYPE	REPLACEMENT REASON
MPC17510EJ	MPC17510EJ Replaced BY MPC17510AEJ	Same Form & Function, Different Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17510EJR2	MPC17510EJR2 Replaced BY MPC17510AEJR2	Same Form & Function, Different Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17511EV	MPC17511EV Replaced BY MPC17511EP	Same Function, Different Form & Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17511EVEL	MPC17511EVEL Replaced BY MPC17511EPR2	Same Function, Different Form & Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17529EV	MPC17529EV Replaced BY MPC17529EJ	Same Function, Different Form & Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17529EVEL	MPC17529EVEL Replaced BY MPC17529EJR2	Same Function, Different Form & Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17531ATEV	MPC17531ATEV Replaced BY MPC17531ATEJ	Same Form & Function, Different Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17531ATEVEL	MPC17531ATEVEL Replaced BY MPC17531ATEJR2	Same Form & Function, Different Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17533EV	MPC17533EV Replaced BY MPC17529EJ	Same Form & Function, Different Fit, Pin-for-Pin Equivalent	Assembly Site
MPC17533EVEL	MPC17533EVEL Replaced BY MPC17529EJR2	Same Form & Function, Different Fit, Pin-for-Pin Equivalent	Assembly Site

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AFFECTED CHANGE CATEGORIES

- ASSEMBLY PROCESS
- ASSEMBLY SITE
- PACKAGE CHANGE

DESCRIPTION OF CHANGE

Freescale Semiconductor received a Product Termination Notification from Mitsui High-Tec, Inc. regarding the closure of the Mitsui Kumanoto package assembly site. As a result of the Mitsui assembly site closure, Freescale Semiconductor announces the device migration of parts associated with three Mitsui package types that will no longer be available: VMFP16, VMFP20 and TSSOPW24. A total of four products will migrate from Mitsui to Amkor Philippines assembly site with JEDEC standard TSSOP packages, and one product will migrate from Mitsui to Freescale Tianjin assembly with QFN package. Final test will be performed at Freescale Tianjin Final Manufacturing (TJNFM) site, Tianjin China.

The new package migration impacts form and fit of the devices. Customers should evaluate the change details and begin planning for conversion based on the last order date and last ship date:
LAST BUY DATE: 30-Sep-2015
LAST SHIP DATE: 31-Mar-2016

Table below summarizes the migration details. Complete Case Outline drawings can be found at Freescale.com

Current Part Number /Tape & Reel	Logical Part Name	Status	Current Mitsui Package	Current Size LxWxH	Current Case Outline	New Migration Part Number /Tape & Reel	New Package	New Size LxWxH	New Case Outline
MPC17510EJ /R2	NOUVEAU	Migrate	TSSOP24	7.9x7.6x1.2	98ASH70455A	MPC17510AEJ /R2	TSSOP20-EP	6.6x6.4x0.95	98ASA00887D
MPC17511EV /EL	PEONY VMFP	Migrate	MFP16 EIAJ-2	5.4x8.1x2.0	98ASA10614D	MPC17511EP /R2	QFN24	4x4x1.2	98ARL10577D
MPC17529EV /EL	STD SMOS MPC17529	Migrate	MFP20 EIAJ-2	7.2x8.1x2.0	98ASA10616D	MPC17529EJ /R2	TSSOP20-EP	6.6x6.4x0.95	98ASA00887D
MPC17531ATEV /EL	GEMINI VMFP	Migrate	MFP20 EIAJ-2	7.2x8.1x2.0	98ASA10616D	MPC17531ATEJ /R2	TSSOP20-EP	6.6x6.4x0.95	98ASA00887D
MPC17533EV /EL	STD SMOS MPC17533	Migrate	MFP16 EIAJ-2	5.4x8.1x2.0	98ASA10614D	MPC17529EJ /R2	TSSOP20-EP	6.6x6.4x0.95	98ASA00887D

REASON FOR CHANGE

Mitsui assembly plant closure - packages will no longer be offered.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

Change to Form and Fit (see summary table above for details). Function and Reliability are unchanged.

Freescale will consider specific conditions of acceptance of this change submitted within 30 days of receipt of this notice on a case by case basis. To request further data or inquire about the notification, please enter a **Service Request.**

For sample inquiries - please go to www.freescale.com

QUAL DATA AVAILABILITY DATE: 05-Dec-2015

QUALIFICATION STATUS: IN PROCESS

QUALIFICATION PLAN:

N/A

RELIABILITY DATA SUMMARY:

Available upon qualification completion.

ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon qualification completion.

CHANGED PART IDENTIFICATION:

N/A

SAMPLE AVAILABILITY DATE: 05-Aug-2015

ATTACHMENT(S):
External attachment(s) FOR this notification can be viewed AT:
16724_Case_Outline_Comparison_Mitsui_Package_Migration.pdf